2023 ASME-CIE GRADUATE RESEARCH POSTER SESSION
Call for Applications

The ASME-CIE Graduate Research Poster session is an opportunity for graduate students in the preliminary phase of their research programs (**MS or within 2 years of starting a Ph.D.**) to present their current work to the CIE research community. This session provides the students a chance to obtain external feedback on their preliminary research that may not yet be ready for presentation at the conference in archival form. The poster session is organized by ASME's Computers and Information in Engineering division (CIE) and will be held during the 2023 ASME IDETC-CIE Conference in Boston, Massachusetts, August 20-23, 2023. The exact date, time, and location of the poster session will be announced in the conference program.

Scope of the Research Posters

The research poster should be relevant to the areas of interest of one or more CIE Technical committees that are listed below:

- Advanced Modeling and Simulation (AMS)
- Computer-Aided Product and Process Development (CAPPD)
- Systems Engineering, Information and Knowledge Management (SEIKM)
- Virtual Environments and Systems (VES)

The areas of interest to each CIE technical committees can be found at: https://idetc.secure-platform.com/a/

Travel Stipends and Eligibility

The ASME-CIE division will offer stipends ($350 for accepted posters) to support graduate students attending the 2023 CIE Conference to present their research posters. Poster submissions reflecting relevant and high-quality research will be favored in the awarding process.

To be eligible for a stipend, the student must be attending a university or college as a graduate student at the time of the 2023 CIE Conference and must be a student member of ASME. Awardees of the CIE stipends are required to attend the conference and present the poster as a condition of the award.

Important Dates

Submission of Application Materials:	**April 10, 2023**
Decision Notification:	**April 24, 2023**
Registration Deadline:	**May 15, 2023**
Submission of final poster:	**July 21, 2023**

Submission of Abstract and Application

To contribute to the research poster session and be considered for the stipend award, all interested applicants must submit a complete application package by the deadline (April 10, 2023) for evaluation.

How to Submit: The application package should be submitted as **a single PDF** file using the conference webtool submission portal (https://idetc.secure-platform.com/a/). Select CIE for Conference, **CIE-26** for Topics, and Student Poster Presentation for Paper Type. Upload the PDF after this. The single-PDF package should include **Application Form**, **Abstract**, and a **Reference Letter from research advisor**. For assistance with submitting your application package online, please email toolboxhelp@asme.org.

Template of the application package can be found at the following link: Link to Application Package template

- **Application**: Use page 1 of the template.
- **Abstract**: Use pages 2-3 of the template .
- **Reference letter from advisor**: Use appropriate institutional letterhead.
- **Single-PDF Package:** Combine the above three documents into one PDF for submission.

The **abstract** could include additional sections or subsections beyond those provided in the template. Please do not change the document's appearance, e.g., margins, font styles, or font sizes, for the sake of uniformity in print. The abstract should not exceed 5 pages, including references.

The **reference letter** from the applicant's research advisor should express the advisor's support for the application. This letter must also state: (1) the applicant's eligibility, (2) the total expected cost of the applicant's travel to the conference, (3) other sources of support available for traveling to the conference, and (4) how the stipend will be spent to bridge the gap between the two.

Submission of Final Research Poster

Successful applicants upon notification are required to prepare a research poster.

Research Poster: Use the provided poster template as a starting point. The size of the poster should be approximately 71 cm (W) x 91.5 cm (H). Only one page is allowed. The poster should contain the following sections: Title; Student and Advisor Contact Information; Abstract of the Work; Research Motivation; Research Questions and Hypotheses; Description of the Work to Date; Description of the Path Forward; Lessons Learned. Additional sections may include software architecture, information models, experimental descriptions, algorithm flow charts, etc. More details on submission will be shared at a later stage. **You'll need to send the file final to ramnath.17@osu.edu** .

How to Present Poster: The applicant is responsible for bringing the printed poster to the conference, ready to be mounted on easels or backing boards. Poster printing services will not be provided by the organizers.

Contact Information

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